ABSTRACT

METHODS AND APPARATUS FOR FLIP-CHIP-ON-LEAD SEMICONDUCTOR PACKAGE

Fabrication of a semiconductor package includes placing a conductive material on a protrusion from a leadframe to form a first assembly, forming a non-conductive mask about the protrusion, and placing a die on the first assembly, the die having an active area. Fabrication can further include reflowing the conductive material to form a second assembly such that a connection extends from the die active area, through the conductive material, to the protrusion. A semiconductor package includes a leadframe having a protrusion, a conductive material reflowed to the protrusion, and a die having an active area coupled to the protrusion by the reflowed solder.

FIG. 1A